ASME
InterPACK 2025
THE INTERNATIONAL TECHNICAL CONFERENCE ON PACKAGING
AND INTEGRATION OF ELECTRONIC AND PHOTONIC MICROSYSTEMS

CALL FOR PAPERS

Special Issue – InterPACK 2025 of ASME Journal of Electronic Packaging

InterPACK is a premier international forum for exchanging state-of-the-art knowledge in research, development, manufacturing, and electronic packaging applications and heterogeneous integration. It is also the flagship conference of the ASME Electronic and Photonic Packaging Division (EPPD). Considering the conclusion of ASME's Information Storage and Processing Systems (ISPS) Division and its associated conference, we are pleased to announce the integration of content from the international conference "MIPE (Micromechatronics for Information and Precision Equipment)," previously co-organized by ISPS and JSME's Information, Intelligence and Precision Equipment (IIP) Division. To honor and continue this legacy, InterPACK 2025 featured three dedicated MIPE-related tracks alongside our traditional program tracks. The Journal of Electronic Packaging (JEP) publishes papers that use experimental and theoretical methods, approaches, and techniques to address and solve various mechanical, materials, thermal, and reliability problems encountered in the analysis, design, manufacturing, testing, and operation of electronic and photonics components, devices, and systems.

Authors are invited to submit their manuscripts revised from their original conference papers to be considered for the Special Issue. These papers will be reviewed by the AE/GE and go through the normal JEP review process. Presentation-only contributors are also invited to develop full-length manuscripts and submit them for review. This InterPACK Special Issue aims to publish outstanding papers with diverse scientific works representing all tracks of InterPACK2025.

Submission Instructions

Should you have any questions, please get in touch with Dr. Jimil Shah at jimilshahphd@gmail.com.

1. The SI is targeted to publish honorary-quality papers with InterPACK2025 flavor, but it's not equivalent to conference proceedings.
2. The submission should be directly revised from the InterPACK2025 paper or technical presentation. Please include the original InterPACK paper in the appendix of your submission to this SI through the ASME Journal Tool.

Topic Areas

The scope of this issue includes but not limited to:

- Heterogeneous Integration
- Data Centers and Modular Edge Systems
- Electronics Packaging
- Power/RF Electronics and Photonics
- Multiscale Thermal Transport and Energy Storage
- Flexible, Wearable, and Printed Electronics
- Transportation Systems, AI and ML
- Micro/Nano Mechatronics, Microelectromechanical Systems and their Applications to Internet of Things
- Mechatronics, Tribology, and Control of Information Storage Systems and Robotics
- Advanced Simulation in Science and Engineering

Publication Dates

2026	Feb 28	Paper Submission Deadline
2026	May 04	Initial Review Completed
2026	Dec	Publication Date

Guest Editors

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